

**MOTOROLA**  
**SEMICONDUCTOR**  
 TECHNICAL DATA

T-33-11  
**MRF477**

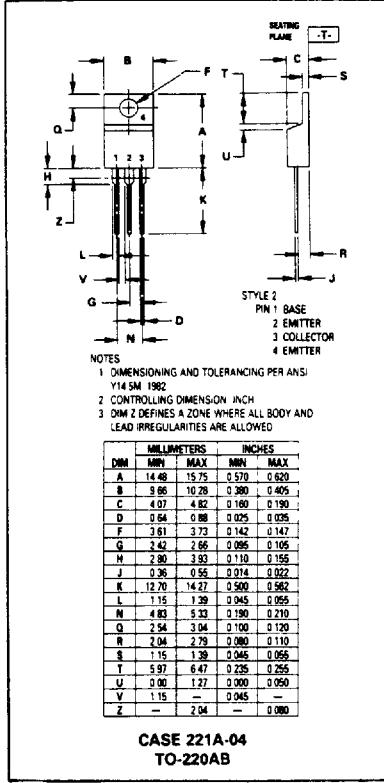
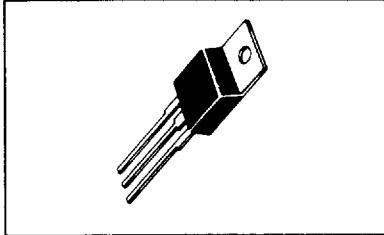
**The RF Line**

**NPN SILICON RF POWER TRANSISTOR**

... designed primarily for application as a high-power linear amplifier from 1.5 to 30 MHz, in single sideband mobile, marine and base station equipment.

- Low-Cost, Common-Emitter TO-220AB Package
- Specified 12.5 Volt, 30 MHz Performance —  
 Output Power = 40 W CW or PEP  
 Power Gain = 15 dB Min  
 Efficiency = 40% Min (PEP)
- Intermodulation Distortion @ 40 W (PEP) —  
 IMD = -30 dB (Max)
- 30:1 VSWR Load Mismatch Capability at Rated Output Power and Supply Voltage

40 W (PEP) — 30 MHz  
**RF POWER TRANSISTOR**  
 NPN SILICON



2

**MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	18	Vdc
Collector Base Voltage	V <sub>CBO</sub>	36	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	40	Vdc
Collector Current — Continuous	I <sub>C</sub>	5.0	Adc
Withstand Current (t = 5.0 s)	—	8.0	Adc
Total Device Dissipation @ T <sub>C</sub> = 25°C (1) Derate above 25°C	P <sub>D</sub>	87.5	Watts W/°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C

**THERMAL CHARACTERISTICS**

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction to Case	R <sub>θJC</sub>	2.0	°C/W

(1) This device is designed for RF operation. The total device dissipation rating applies only when the device is operated as an RF amplifier.

MRF477

MOTOROLA SC (XSTRS/R F)

46E D

6367254 0094693 6

MOT6

T-33-11

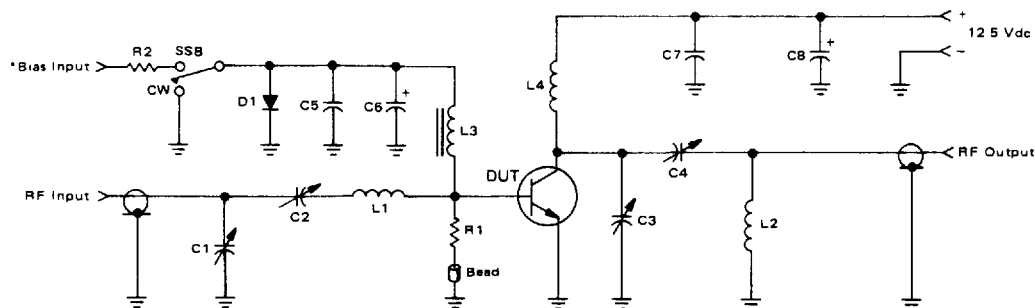
2

ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Collector-Emitter Breakdown Voltage (I <sub>C</sub> = 100 mA, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	18	—	—	Vdc
Collector Base Breakdown Voltage (I <sub>C</sub> = 100 mA, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	36	—	—	Vdc
Emitter-Base Breakdown Voltage (I <sub>E</sub> = 5.0 mA, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	4.0	—	—	Vdc
Collector Cutoff Current (V <sub>CE</sub> = 12.5 Vdc, V <sub>BE</sub> = 0, T <sub>C</sub> = 25°C)	I <sub>CES</sub>	—	—	10	mA
<b>ON CHARACTERISTICS</b>					
DC Current Gain (I <sub>C</sub> = 2.0 A, V <sub>CE</sub> = 5.0 Vdc)	h <sub>FE</sub>	20	70	—	—
<b>DYNAMIC CHARACTERISTICS</b>					
Output Capacitance (V <sub>CB</sub> = 12.5 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>ob</sub>	—	175	250	pF
<b>FUNCTIONAL TESTS</b>					
Common-Emitter Amplifier Power Gain (V <sub>CC</sub> = 12.5 Vdc, P <sub>out</sub> = 40 W (PEP), f <sub>1</sub> = 30 MHz, f <sub>2</sub> = 30.001 MHz, I <sub>CQ</sub> = 40 mA)	G <sub>PE</sub>	15	17	—	dB
Collector Efficiency (V <sub>CC</sub> = 12.5 Vdc, P <sub>out</sub> = 40 W (PEP), f <sub>1</sub> = 30 MHz, f <sub>2</sub> = 30.001 MHz, I <sub>CQ</sub> = 40 mA)	η	40	45	—	%
Intermodulation Distortion (1) (V <sub>CC</sub> = 12.5 Vdc, P <sub>out</sub> = 40 W (PEP), f <sub>1</sub> = 30 MHz, f <sub>2</sub> = 30.001 MHz, I <sub>CQ</sub> = 40 mA)	IMD (d <sub>3</sub> )	—	-35	-30	dB

(1) To Proposed EIA Method of Measurement Reference Peak Envelope Power

FIGURE 1 - 30 MHz TEST CIRCUIT



- C1, C2, C4 - Arco 469, 190-780 pF
- C3 - Arco 429, 90-400 pF
- C5, C7 - 0.001 μF Disk Ceramics
- C6 - 500 μF 3.0 Vdc Electrolytic
- C8 - 100 μF 16 Vdc Electrolytic
- R1 - 10 Ω 1.0 Watt Resistor
- R2 - 5 Ω 5.0 Watt Resistor

- L1 - 4 Turns #16 AWG 1/3" ID, 1/3" Long
- L2 - 3 Turns #16 AWG 1/3" ID, 1/2" Long
- L3 - 10 μH Molded Choke
- L4 - 12 Turns #18 AWG 1/4" ID
- Bead - Ferroxcube #56 590-65/38
- D1 - 1N4719

\*Adjust Bias (Base) Voltage for I<sub>CQ</sub> = 40 mA with no RF applied.

MRF477

MOTOROLA SC (XSTRS/R F) 46E D ■ 6367254 0094694 8 ■ MOT6

T-33-11

FIGURE 2 - OUTPUT POWER versus INPUT POWER

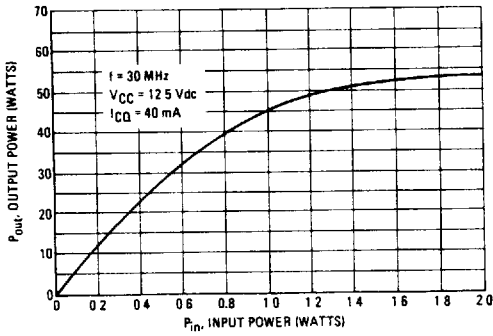


FIGURE 3 - OUTPUT POWER versus SUPPLY VOLTAGE

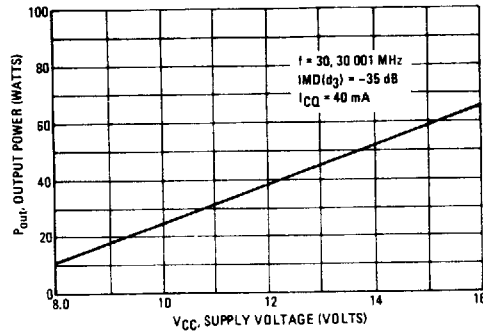


FIGURE 4 - POWER GAIN versus FREQUENCY

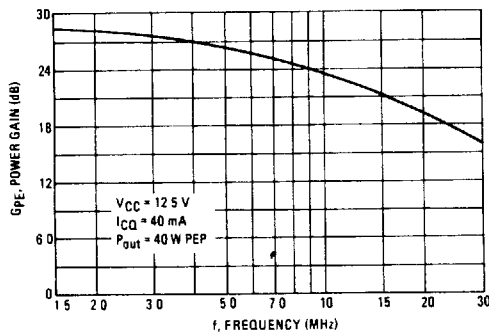


FIGURE 5 - INTERMODULATION DISTORTION versus OUTPUT POWER

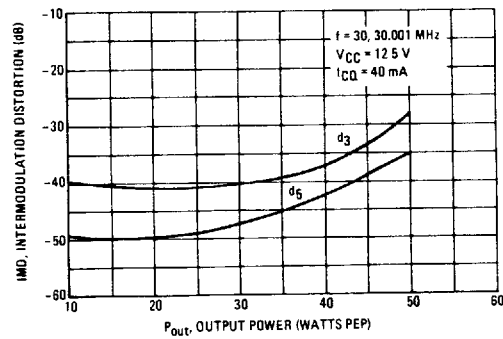
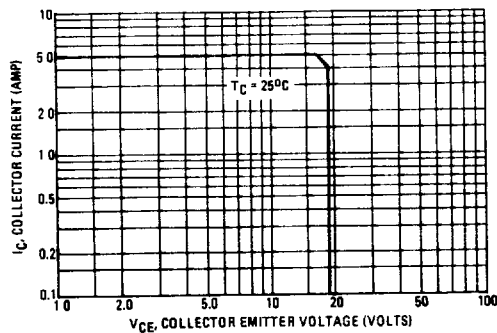


FIGURE 6 - SAFE OPERATING AREA



2

MRF477

MOTOROLA SC (XSTRS/R F)

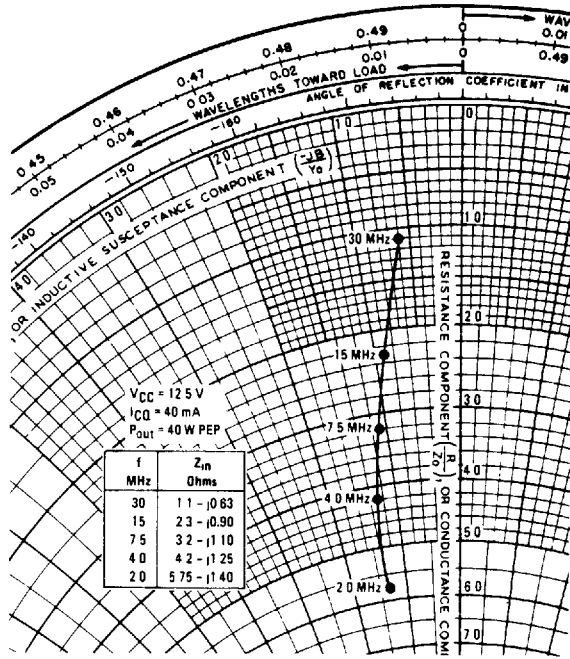
46E D

6367254 0094695 T

MOT6

T-33-11

FIGURE 7 - SERIES EQUIVALENT INPUT IMPEDANCE



2

FIGURE 8 - OUTPUT CAPACITANCE versus FREQUENCY

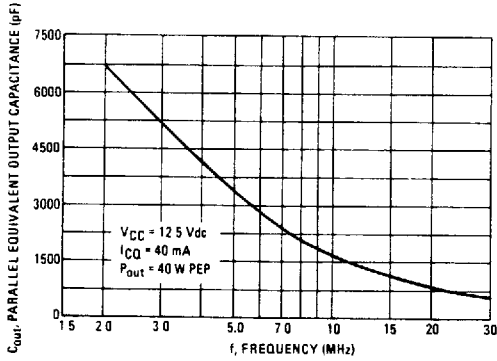


FIGURE 9 - OUTPUT RESISTANCE versus FREQUENCY

